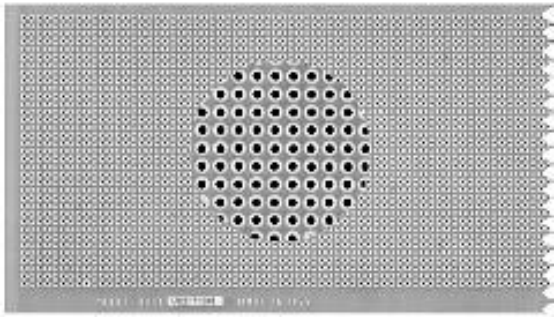
8010 4.0" x 13.0"

Circuit Pattern:	Pad-Per-Hole
Contacts:	N/A
Width/Thick:	12.86"/.062"
Height:	4.00"
Contacts:	N/A
16-Pin DIP Capacity:	124
Material:	FR4 Epoxy Glass
Wire-Wrap Terminals:	T44, T46, T49, T68,
Solder Terminals:	T42-1
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

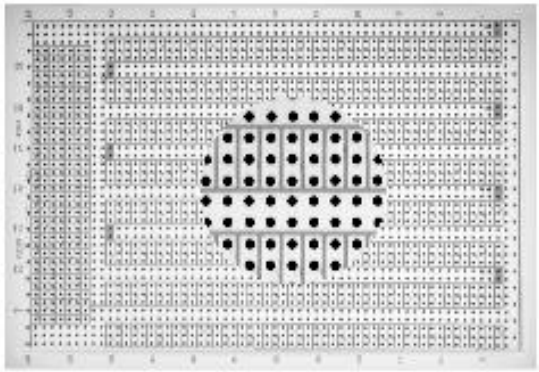
- *Precision-Drilled, plated-thru holes*
- *0.080" diameter, isolated solder pad around each hole*
- *Board size and surface area approximate Macintosh II specifications*
- *Unrestricted component placement*



8001 4.50" x 6.5"

Circuit Pattern:	3-Hole Solder Pad
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	20
Material:	CEM-1
Solder Terminals:	T42-1, K24C, K31C
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

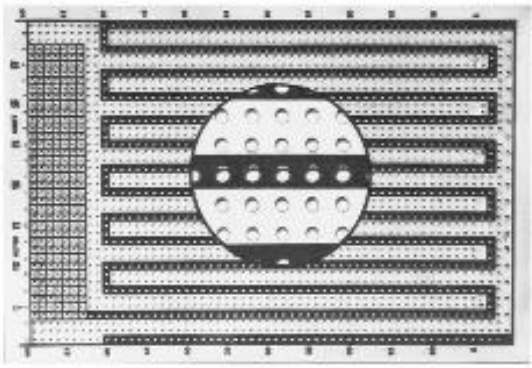
- *Circuit pattern etched onto wiring side only*
- *Solder mount DIP sockets or IC devices with any lead spacing*
- *3-hole solder pads (0.28" X 0.080") for interconnecting multiple component leads*



8002 4.5" x 6.5"

Circuit Pattern:	Interleaved Buses
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	36
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

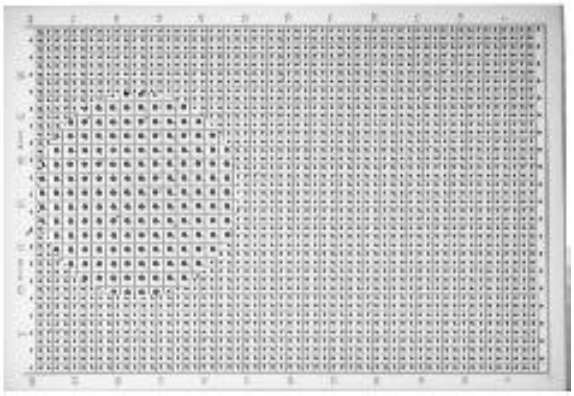
- *Ideal for wire-wrap applications*
- *Power and ground buses etched onto wiring side only*
- *Bus surfaces solder coated for user convenience*
- *Mount components with 0.3", 0.6" and 0.9" lead spacing*
- *I/O area with solder pads for mounting connector*



8003 4.5" x 6.5"

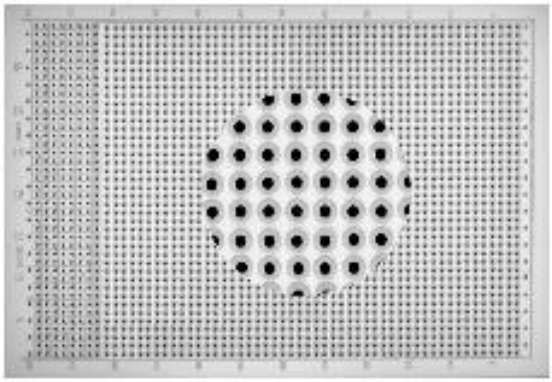
Circuit Pattern:	Pad-Per-Hole
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	60
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46. T49. T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Square solder pad etched around each hole on wiring side*
- *Accommodates any type DIP IC device or discrete component*



Products

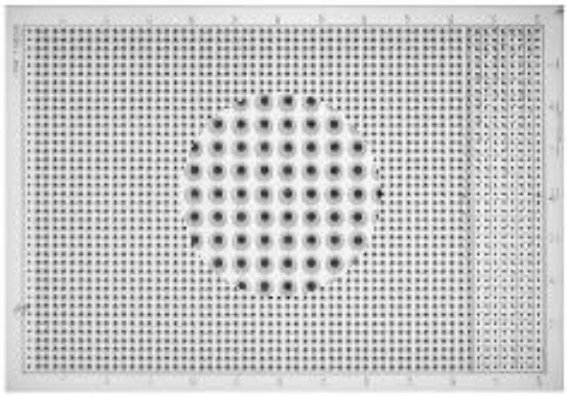
11115 Vanowen St., North Hollywood, CA 91605 Phone(818)985-8208 Fax(818)985-7708
Toll-Free (800) 423-5659
Web site: http://www.vectorelect.com
VECTOR ELECTRONIC COMPANY



8004 4.5" x 6.5"

Circuit Pattern:	Ground Plane
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	50
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

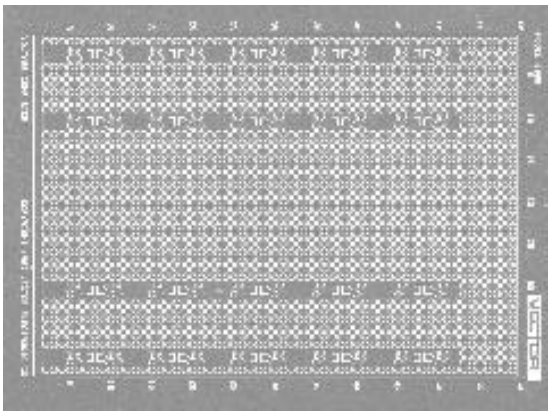
- *To commit wire-wrap pins to voltage and ground planes, use Vector T124 solder washers, available separately*
- *0.085" diameter clearance around holes*
- *Etched overall ground plane on wiring side only*
- *Plane surfaces solder-coated for user convenience*
- *I/O area with solder pads for mounting connector*



8007 4.5" x 6.5"

Circuit Pattern:	Pad-Per-Hole/ Ground Plane
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	60
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

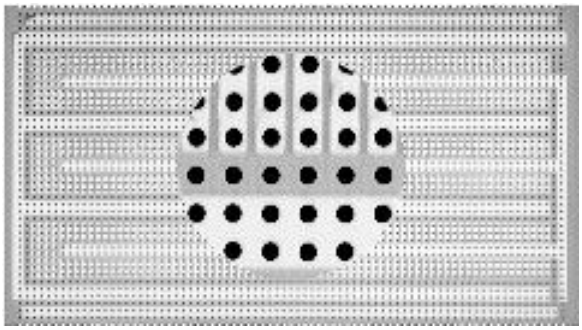
- *Pad-Per-Hole pattern on component side - overall Ground Plane pattern on wiring side*
- *To commit wire-wrap pins to ground planes, use Vector T124 solder washers, available separately*
- *0.080" diameter, isolated solder pad around holes, component side*
- *Accommodates any type DIP IC device or discrete component*
- *Plane and pad surfaces solder-coated for user convenience*



8008 4.5" x 6.5"

Circuit Pattern:	Pads & Planes
Contacts:	N/A
Width/Thick:	6.50"/.062"
Height:	4.50"
16-Pin DIP Capacity:	70
Material:	FR4 Epoxy Glass
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Unique circuit pattern features full voltage and ground planes on opposite sides with isolated, plated-thru holes*
- *0.080" diameter, isolated solder pad around holes, component side*
- *Plane surfaces solder-coated for user convenience*
- *SMD cap positions for discrete decoupling capacitors*

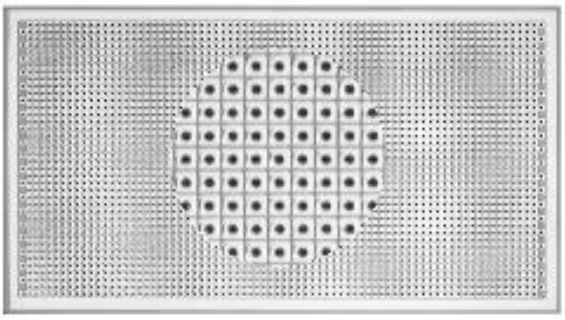


3677-6 4.5" x 8.08"

Circuit Pattern:	3-Hole Solder Pad
Contacts:	N/A
Width/Thick:	8.08"/.062"
Height:	4.50"
16-Pin DIP Capacity:	21
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Etched circuit pattern on wiring side only*
- *0.080" diameter, isolated solder pad around holes, both sides*
- *3-hole solder pads (0.028" X 0.080") for interconnecting multiple component leads*
- *Pad and bus surfaces solder-coated for user convenience*

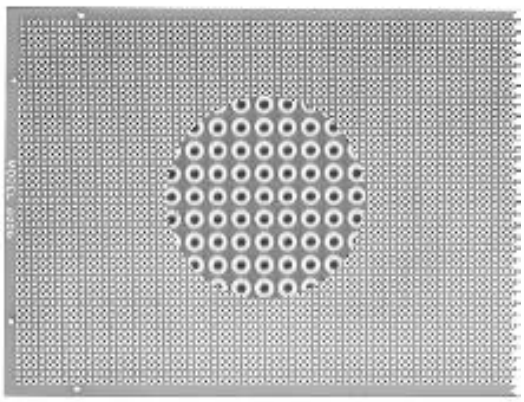
45P80-1 4.5" x 8.08"



Circuit Pattern:	Pad-Per-Hole
Contacts:	N/A
Width/Thick:	8.08"/.062"
Height:	4.50"
16-Pin DIP Capacity:	80
Material:	CEM-1
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Isolated, square pads around each hole*

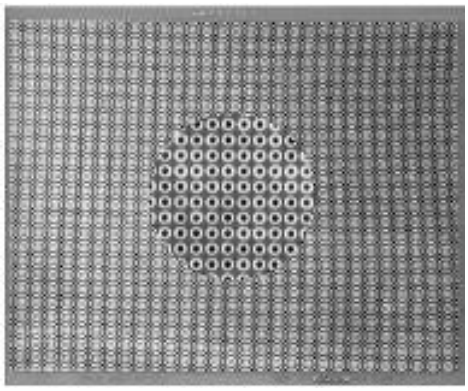
8006 5.0" x 13.25"



Circuit Pattern:	Pad-Per-Hole
Contacts:	N/A
Width/Thick:	13.25"/.062"
Height:	5.00"
16-Pin DIP Capacity:	154
Material:	FR4 Epoxy Glass
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, 49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Copper plated-thru holes*
- *0.080" diameter, isolated solder pad around holes, both sides*
- *Unrestricted component place ment, extended area for high density applications*
- *Board can be cut down into smaller units*

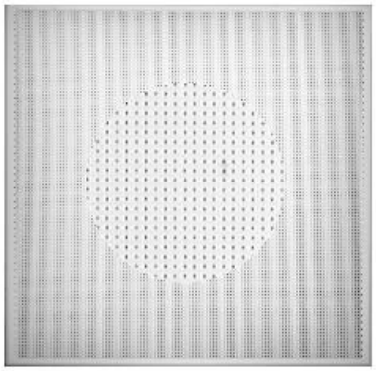
8012 9.2" x 11.0"



Circuit Pattern:	Pad-Per-Hole
Contacts:	N/A
Width/Thick:	11.00"/.062"
Height:	9.20"
16-Pin DIP Capacity:	283
Material:	FR4 Epoxy Glass
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Plated-thru holes*
- *Approximates Eurocard (DIN) specifications: 6U x 280MM, can be sheared down to 6U x 220MM, or 160MM*
- *0.080" diameter, isolated solder pad around holes*
- *Unrestricted component placement, extended area for high density applications*

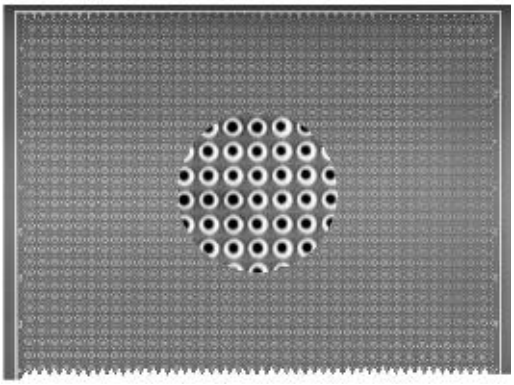
11115 Vanowen St., North Hollywood, CA 91605 Phone(818)985-8208 Fax(818)985-7708
Toll-Free (800) 423-5659
Web site: http://www.vectorelect.com
VECTOR ELECTRONIC COMPANY



106P106-1 10.6" x 10.6"

Circuit Pattern:	Pad-Per-Hole
Contacts:	N/A
Width/Thick:	10.60"/.062"
Height:	10.60"
16-Pin DIP Capacity:	275
Material:	FR4 Epoxy Glass
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

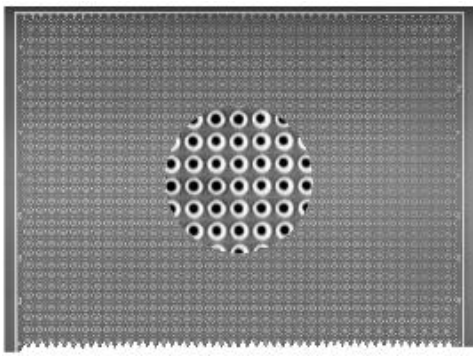
- *0.080" diameter, isolated solder pad around each hole, both sides*



106P180-4 10.6" X 18.0"

Circuit Pattern:	Pad-Per-Hole & Ground Plane, 2 sides
Contacts:	N/A
Width/Thick:	10.60"/.062"
Height:	18.00
16-Pin DIP Capacity:	400
Material:	FR4 Epoxy Glass
Solder Terminals:	T42
Wire-Wrap Terminals:	T44, T46, T49,T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Individual pads with plated-thru holes*
- *Etched ground plane surrounds pads on both sides*
- *0.080" diameter, isolated solder pad around each hole, both sides*



106P70-4 7.0" x 10.6"

Circuit Pattern:	Pad-Per-Hole & Ground Plane
Contacts:	N/A
Width/Thick:	7.0"/.062"
Height:	10.60"
16-Pin DIP Capacity:	175
Material:	FR4 Epoxy Glass 2 sides
Solder Terminals:	T42-1
Wire-Wrap Terminals:	T44, T46, T49, T68
Wire-Wrap Socket Pins:	R32
Hole Diameter:	.042"

- *Individual pads with plated-thru holes*
- *Etched ground plane surrounds pads on both sides*
- *0.080" diameter, isolated solder pad around each hole, both sides*